D1FM3

Schottky Barrier Diodes

30V, 5A

Feature

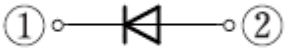
- Small SMD
- High Recovery Speed
- Low V_F
- Based on AEC-Q101
- Pb free terminal
- RoHS:Yes

OUTLINE

Package (House Name): 1F
Package (JEDEC Code): DO-214AC



Equivalent circuit



Absolute Maximum Ratings (unless otherwise specified : Tc=25°C)

Item	Symbol	Conditions	Ratings	Unit
Storage temperrature	Tstg		-55 to 150	°C
Junction temperature	Tj		-55 to 150	°C
Repetitive peak reverse voltage	V_{RRM}		30	V
Average forward current	I_F(AV)	50Hz sine wave, Resistance load, On glass-epoxy substrate, Tc=83°C ※	5	A
Average forward current	I_F(AV)	50Hz sine wave, Resistance load, On glass-epoxy substrate, Ta=25°C ※	3	A
Surge forward current	I_{FSM}	50Hz sine wave, Non-repetitive, 1cycle, Peak value, Tj=25°C	90	A

※ ：See the original Specifications

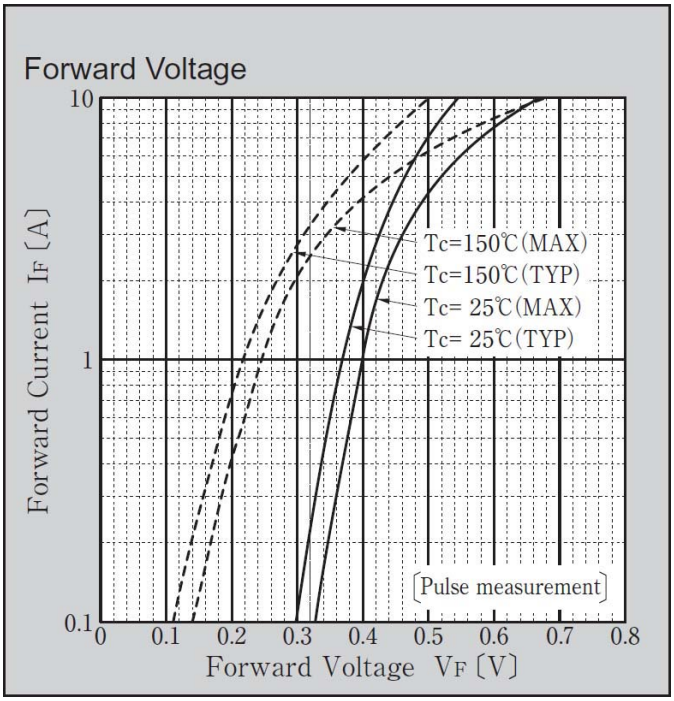
Electrical Characteristics (unless otherwise specified : Tc=25°C)

Item	Symbol	Conditions	Ratings			Unit
			MIN	TYP	MAX	
Forward voltage	V_F	IF=3.0A, Pulse measurement			0.46	V
Forward voltage	V_F	IF=1.0A, Pulse measurement			0.4	V
Reverse current	I_R	VR=30V, Pulse measurement			0.1	mA
Total capacitance	Ct	f=1MHz, VR=10V		130		pF
Thermal resistance	Rth(j-c)	Junction to case ※			16	°C/W
Thermal resistance	Rth(j-l)	Junction to lead, On glass-epoxy substrate ※			18	°C/W
Thermal resistance	Rth(j-a)	Junction to ambient, On glass-epoxy substrate ※			65	°C/W

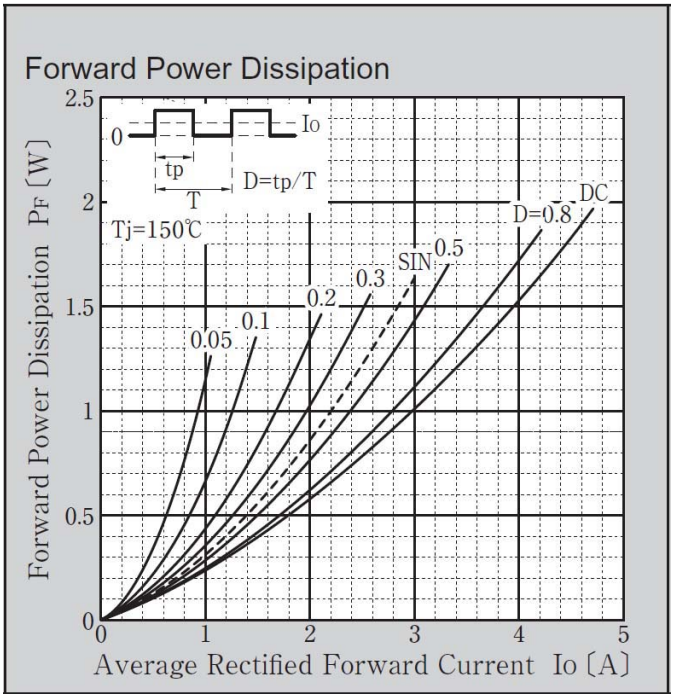
※ ：See the original Specifications

CHARACTERISTIC DIAGRAMS

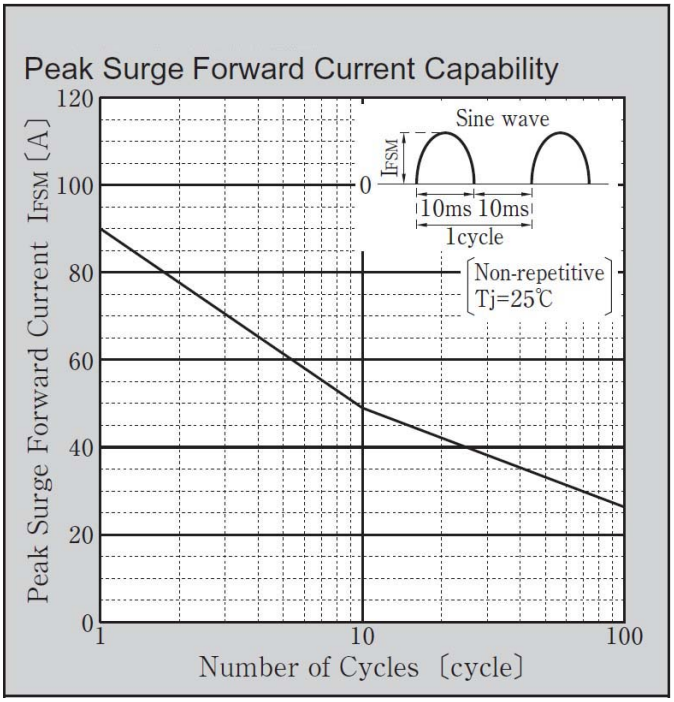
Forward Voltage



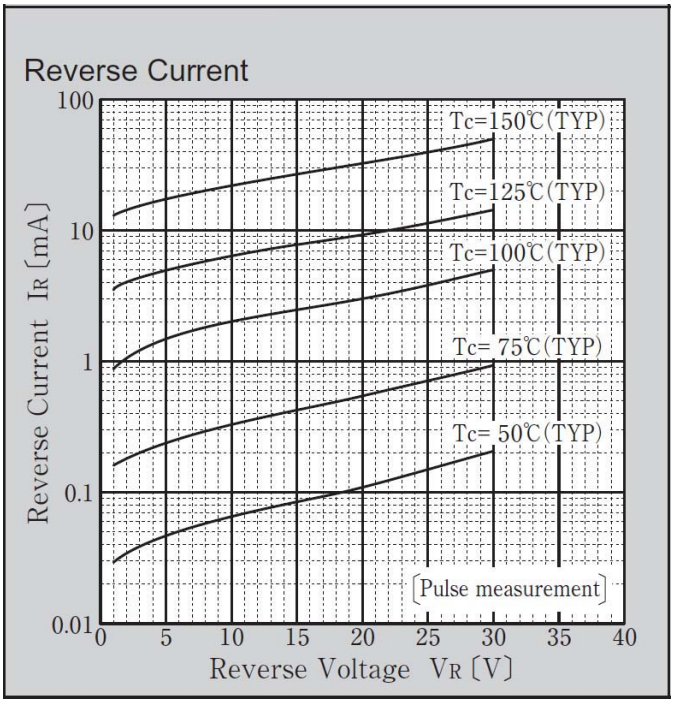
Forward Power Dissipation



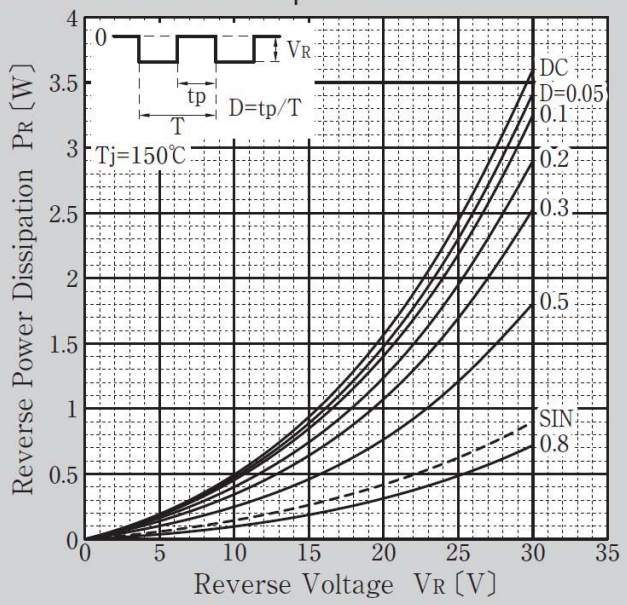
Peak Surge Forward Current Capability



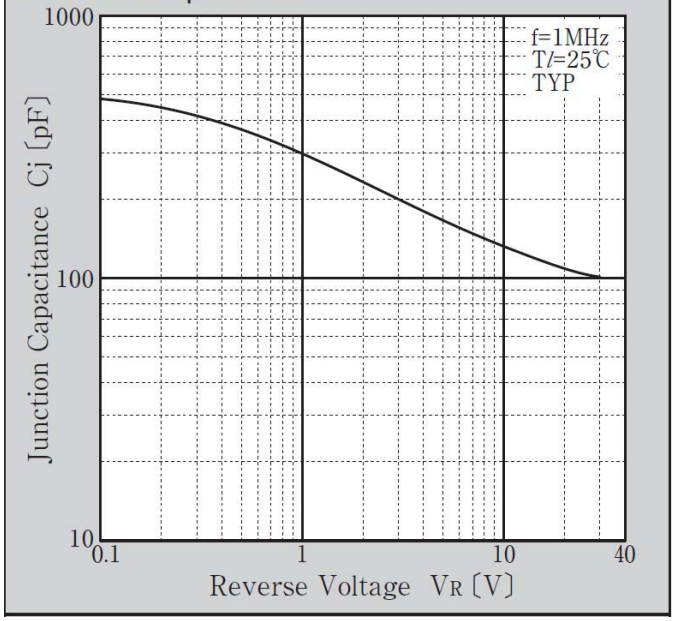
Reverse Current



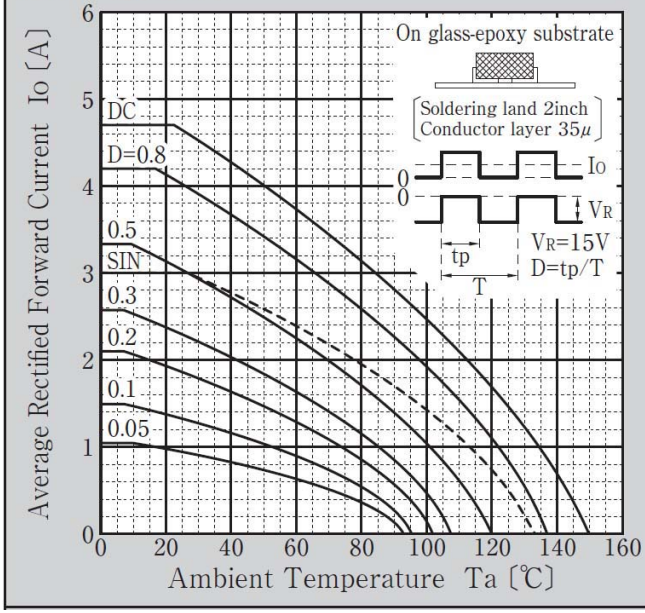
Reverse Power Dissipation



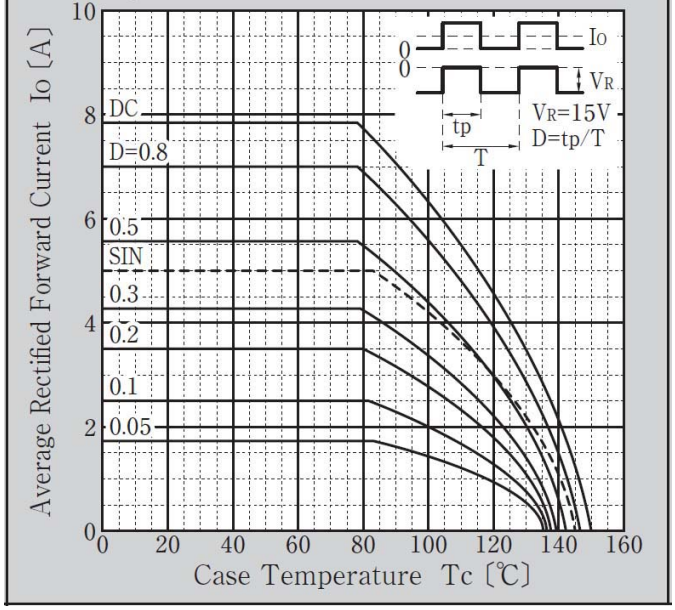
Junction Capacitance



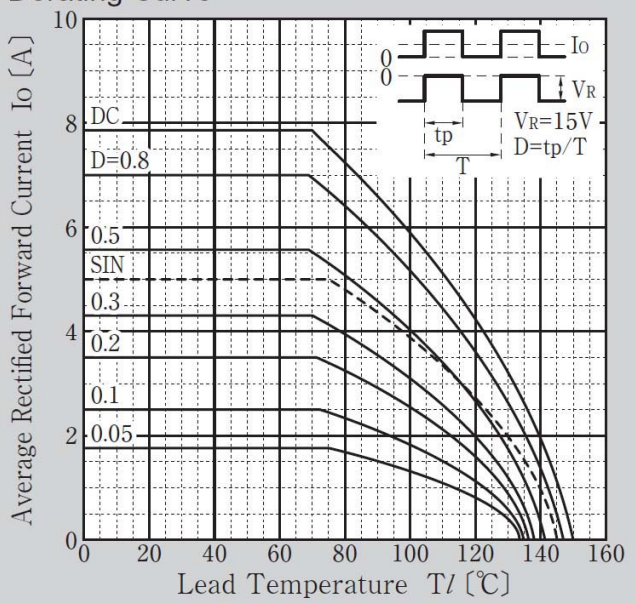
Derating Curve



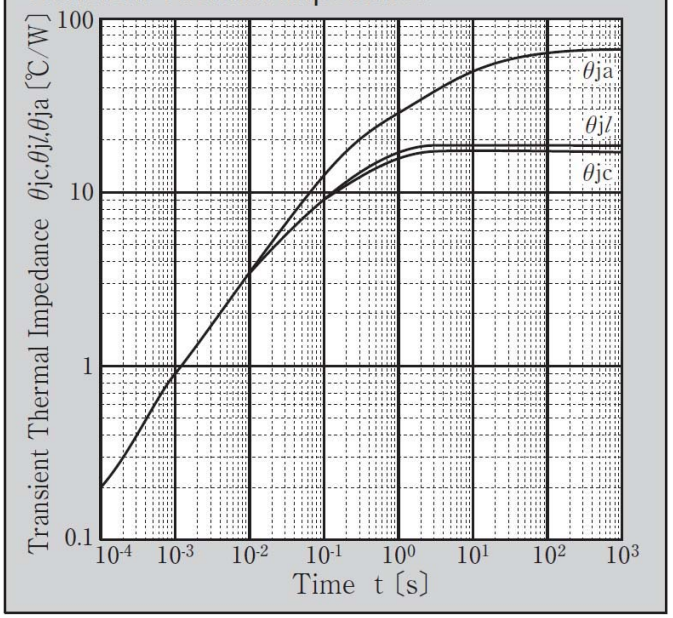
Derating Curve



Derating Curve



Transient Thermal Impedance



Outline Dimensions

unit:mm

B3

JEDEC Code	DO-214AC
JEITA Code	–
House Name	1F, CF

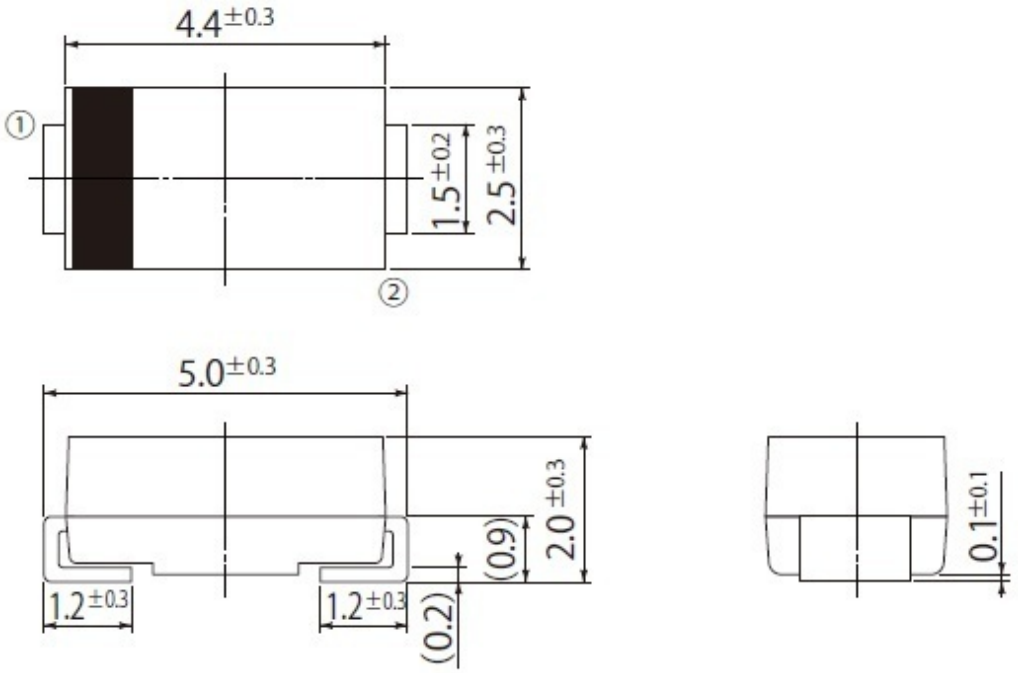
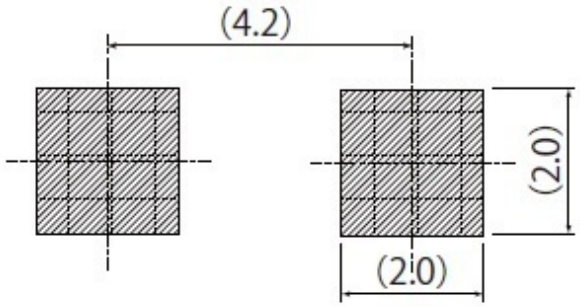


Fig. B3-1 ① ②



Referential Soldering Pad

- Optimize soldering pad to the board design and soldering condition.

- The content specified herein is subject to change for improvement without notice.
- If you wish to use any such products, please be sure to refer to the specifications.

U182-1 (2026.08)

Notes

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   【Special applications】
   Transportation equipment (vehicles, ships, etc.), trunk-line communication equipment, traffic signal control systems, anti-disaster/crime systems, safety equipment, medical equipment, etc.
   【Specific applications】
   Nuclear reactor control systems, aircraft, aerospace equipment, submarine repeaters, life support equipment and systems, etc.
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